

Thermal conductive paste GD900, 0.5g

Reference: AM1605

EAN13: -

HS code: 38249996



Product attributes:

Product features:

Color: Gray

Max. operating temperature: 200 °C

Thermal conductivity: 4.8 W/mK

Product description:

High-quality heat sink paste with thermal conductivity up to 4.8W/mK. The thermal paste is designed to ensure better heat transfer between the heat source - electronic component and its heat sink. It fills the unevenness between the surface of the heat sink and the surface of the cooled component and thus increases the heat transfer to the heat sink, which then has greater cooling efficiency. By using a heat conductive paste, you will improve the overall cooling efficiency and extend the life of the cooled components. Suitable for all semiconductors (LEDs), processors, graphics cards, memory modules and more. The paste is not electrically conductive.

Thermal conductivity: 4.8W/mK

Minimum operating temperature: -50°C

Maximum operating temperature: 200°C

Specific gravity

